

H 3146

Field of the Invention

Background of the Invention

Polyacrylate jointing compounds are known. Thus, WO 97/07173

describes a jointing compound of a butyl acrylate/styrene copolymer, epoxystearic acid methyl ester, chalk, TiO_2 , ammonia, wetting agent and water (see page 26). This known jointing compound has a resilience of 22% when the test specimen is elongated by 100% and allowed to relax for 1 hour after 24 hours at room temperature. The E 100 modulus (= offset yield stress at 100% elongation) is 0.04 for concrete, 0.05 for wood, 0.015 for PVC and 0.06 N/mm² for aluminium.

WO 96/06897 describes a composition of a homopolybutyl acrylate and an epoxystearic acid methyl ester (see page 21, Example 4). Compositions of this type are particularly suitable for the production of paste-form sealants, such as jointing compounds (see page 13, last paragraph).

Although compositions of the type in question may be used as a joining compound with a low requirement profile, they cannot be regarded as elastic joining compounds. To this end, they have to meet the following requirement: their resilience must be $> 70\%$, corresponding to IVD-Merkblatt No. 2. Resilience is measured in accordance with ISO 7389, Method B.

Summary of the Invention

The problem addressed by the present invention was to provide high-quality jointing compounds which would be distinguished not only by high elasticity, but also by universal adhesion without primers to the substrates